

# Phase 2 Module Meeting 8/14/2014

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- Phase 2 CT2015 modules/mechanics proposal submitted last week
- PO for Sensor development with Novati launched
  - Confirmed that BNL will supply wafers
  - SLAC will consult on process
  - Starting to design structures
- Dummy sensor wafers sent to UCD
  - Packaged with ROIC wafers and sent to vendor
  - Should look at other possible vendors?
  - Need to document visual flaws (location and wafer #)

# Thermal Model Discussion

Discuss of thermal module prototype plans:

- Thermal tests of bump bonded structure on LB structure
- Develop minimal thermal module design for module testing
  - Kapton heaters
  - Dummy module + top sensor
  - Al-CF support
  - Accurate glue layers
  - Kapton structures
  - CF structures (is high modulus fiber available)?
  - Build and test ...
- Model and build short prototype support rod
- Combine with module thermal model
- Tech and engineer support??